

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	75	V
Working Peak Reverse Voltage	V _{RWM}		
Forward Continuous Current (Note 5)	I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs	I _{FSM}	2.0	A
@ t = 1.0s		1.0	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	75	—	V	I _R = 100μA
Forward Voltage	V _F	0.55 0.67 0.75 —	0.70 0.82 1.10 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 6)	I _R	—	1.0 3.0 100 25	μA μA μA nA	V _R = 50V V _R = 100V V _R = 50V, T _J = +125°C V _R = 20V
Total Capacitance	C _T	—	2.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 × I _R , R _L = 100Ω

- Notes:
- Part mounted on FR-4 substrate printed circuit board with 1 inch square 2oz copper pad area.
 - Short duration pulse test used to minimize self-heating effect.

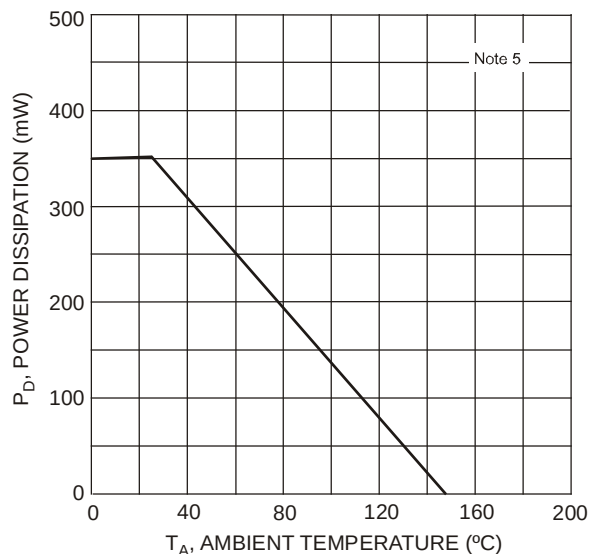


Figure 1 Power Derating Curve, Total Package

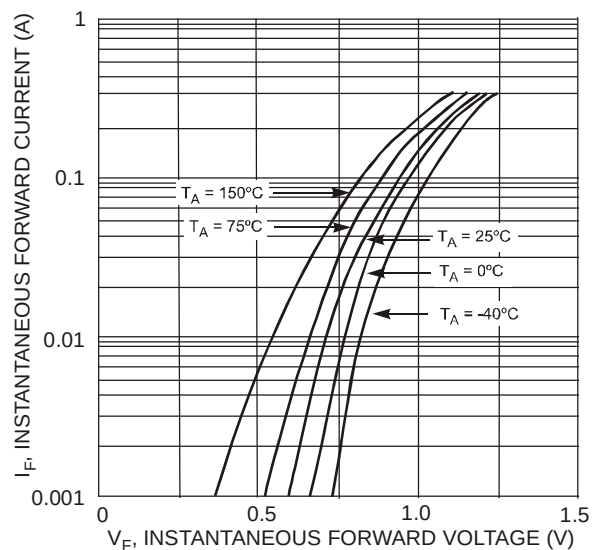


Figure 2 Typical Forward Characteristics, Per Element

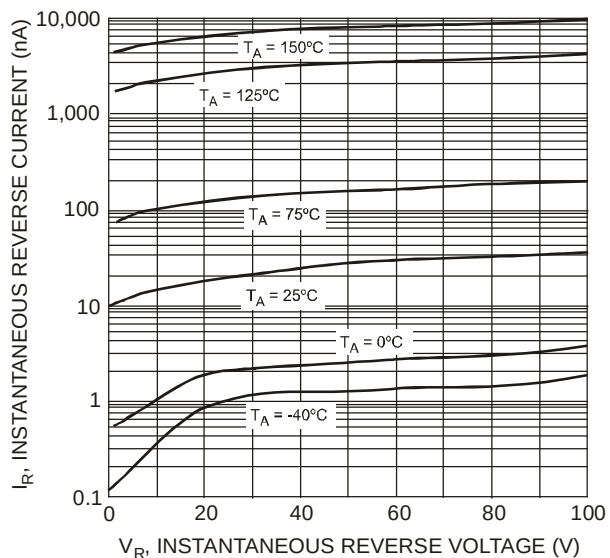


Figure 3 Typical Reverse Characteristics, Per Element

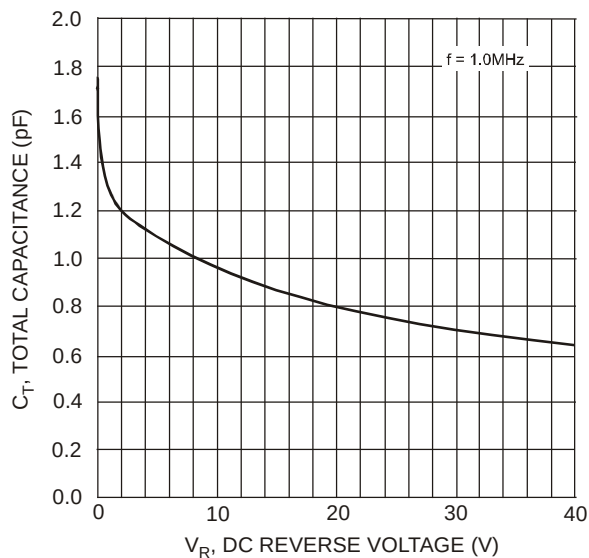
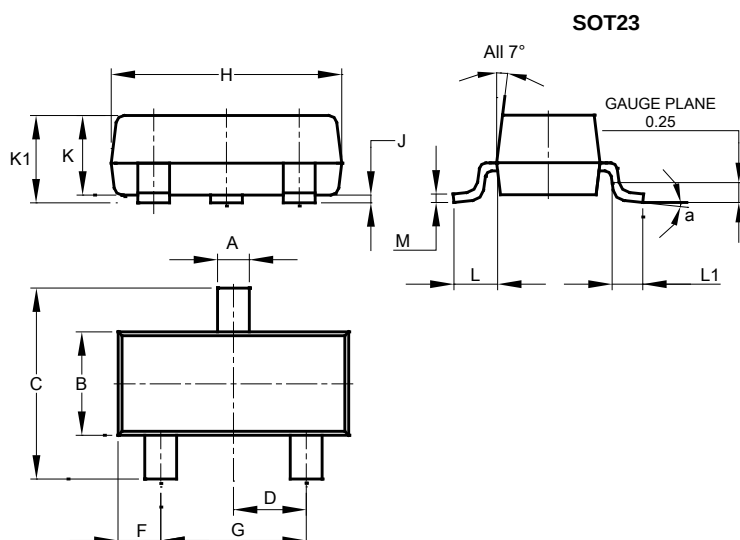


Figure 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

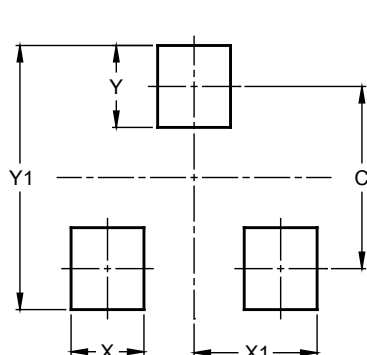
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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